



AOL1414

N-Channel Enhancement Mode Field Effect Transistor



General Description

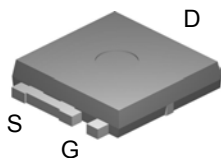
The AOL1414 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and low gate resistance. This device is ideally suited for use as a high side switch in CPU core power conversion. *Standard Product AOL1414 is Pb-free (meets ROHS & Sony 259 specifications). AOL1414L is a Green Product ordering option. AOL1414 and AOL1414L are electrically identical.*

Features

V_{DS} (V) = 30V
 I_D = 85A (V_{GS} = 10V)
 $R_{DS(ON)} < 6.5m\Omega$ (V_{GS} = 10V)
 $R_{DS(ON)} < 7.5m\Omega$ (V_{GS} = 4.5V)

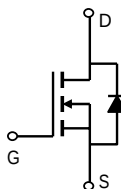
UIS Tested
 Rg, Ciss, Coss, Crss Tested

Ultra SO-8™ Top View



Fits SOIC8 footprint !

Bottom tab connected to drain



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^B	I_D	85	A
$T_C=25^\circ\text{C}$		70	
$T_C=100^\circ\text{C}$	I_{DM}	200	
Pulsed Drain Current		21	
Continuous Drain Current ^G	I_{DSM}	17	A
$T_A=25^\circ\text{C}$		17	
$T_A=70^\circ\text{C}$	I_{AR}	30	A
Avalanche Current ^C	E_{AR}	135	mJ
Repetitive avalanche energy $L=0.3mH$ ^C	P_D	100	W
Power Dissipation ^B	P_{DSM}	50	W
$T_C=25^\circ\text{C}$		5	
$T_C=100^\circ\text{C}$	P_{DSM}	3	
Power Dissipation ^A	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$
Junction and Storage Temperature Range			

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	19.5	25	$^\circ\text{C/W}$
$t \leq 10s$		48	60	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A	$R_{\theta JC}$	1	1.5	$^\circ\text{C/W}$
Steady-State				
Maximum Junction-to-Case ^C				

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =55°C		0.002	1	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±12V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V	100			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A T _J =125°C		4.9	6.5	mΩ
				6.9	8.3	
		V _{GS} =4.5V, I _D =20A		6	7.5	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		90		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.74	1	V
I _S	Maximum Body-Diode Continuous Current				85	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		2100	2520	pF
C _{oss}	Output Capacitance			536		pF
C _{rss}	Reverse Transfer Capacitance			165		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		0.95	1.5	Ω
SWITCHING PARAMETERS						
Q _g (4.5V)	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =20A		19.7	24	nC
Q _{gs}	Gate Source Charge			3.6		nC
Q _{gd}	Gate Drain Charge			7.9		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω		5.9	10	ns
t _r	Turn-On Rise Time			11	17	ns
t _{D(off)}	Turn-Off DelayTime			36.2	55	ns
t _f	Turn-Off Fall Time			12	18	ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		35	42	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=100A/μs		33	50	nC

A: The value of R_{θJA} is measured with the device in a still air environment with T_A=25°C.

B: The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C.

D: The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

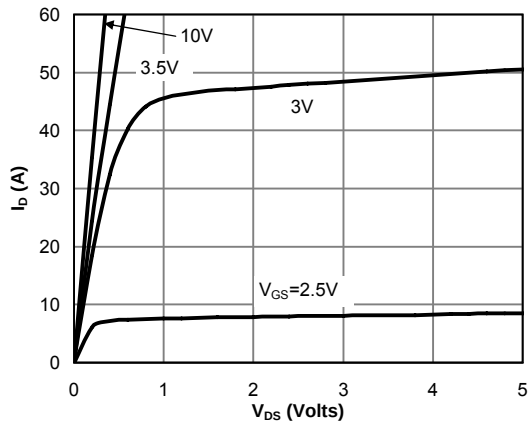


Fig 1: On-Region Characteristics

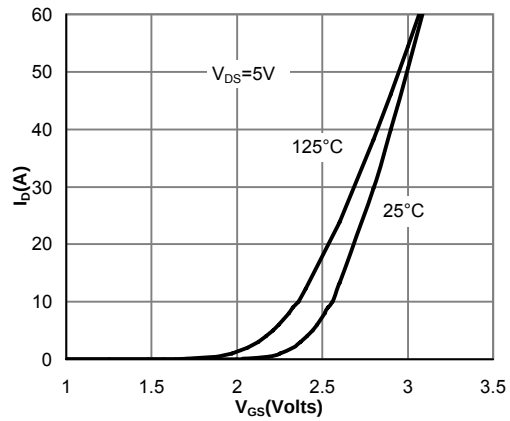


Figure 2: Transfer Characteristics

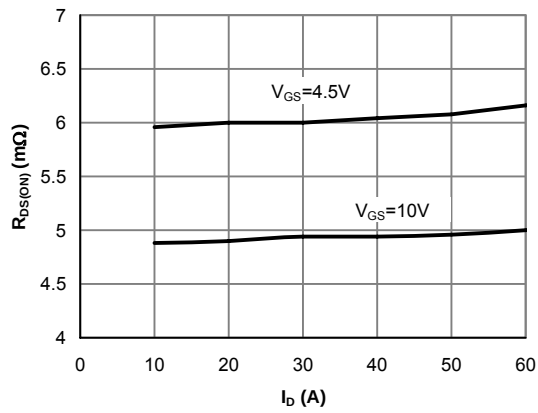


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

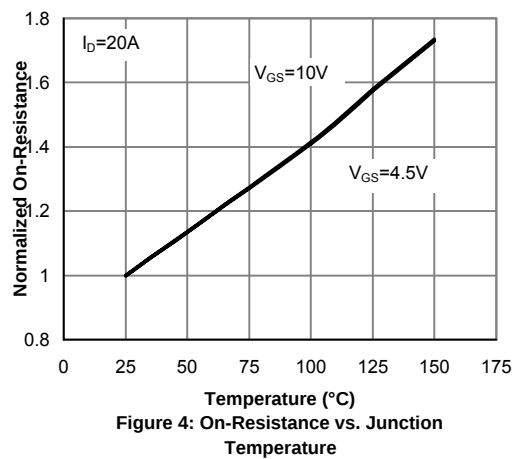


Figure 4: On-Resistance vs. Junction Temperature

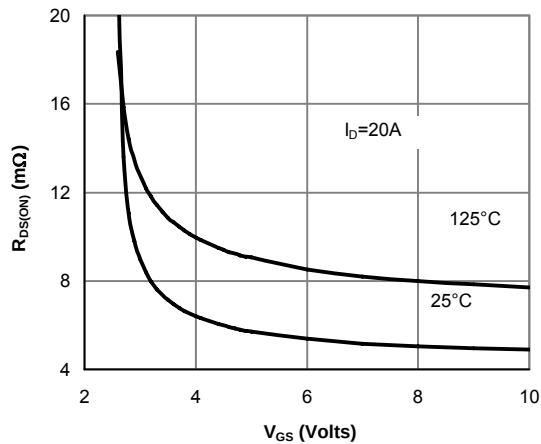


Figure 5: On-Resistance vs. Gate-Source Voltage

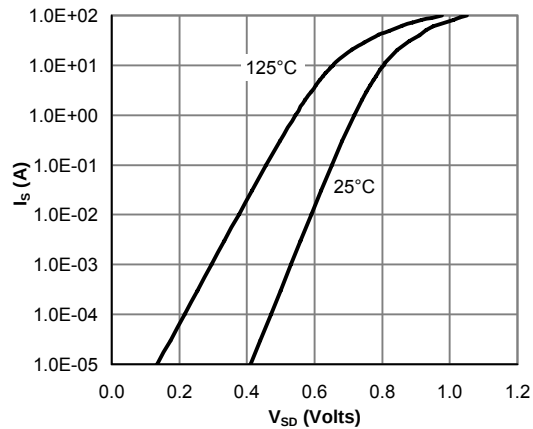
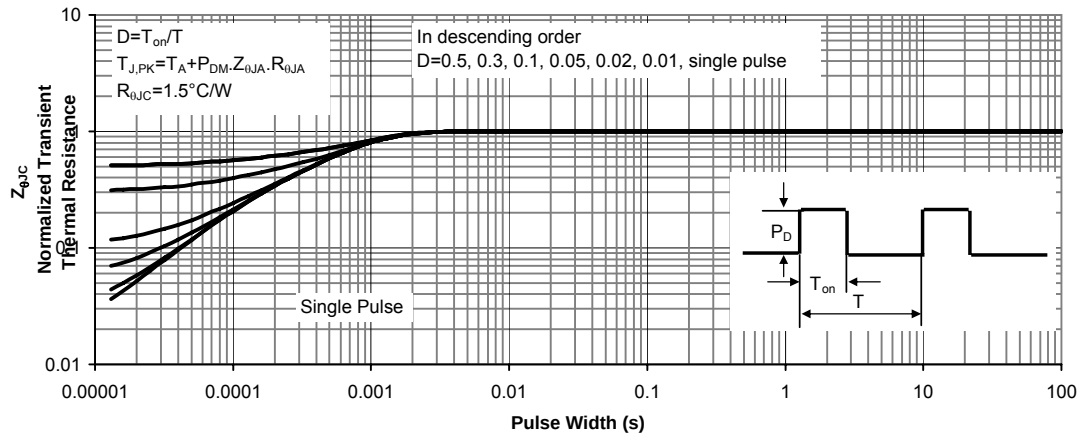
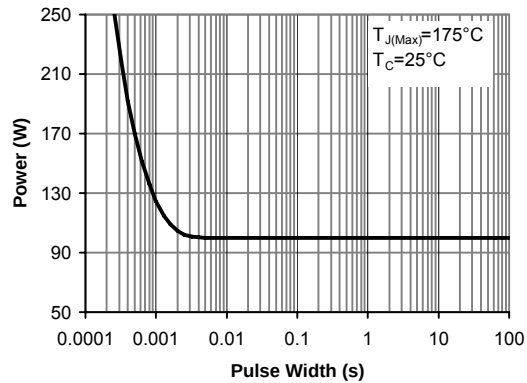
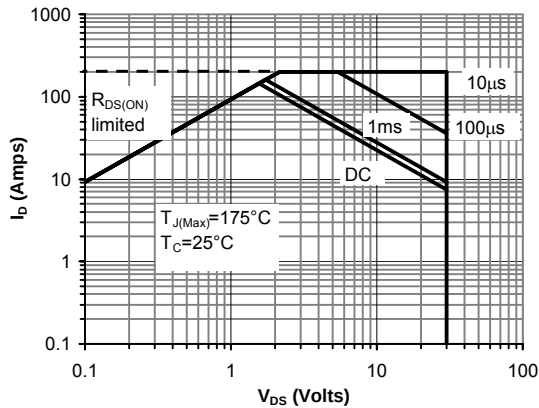
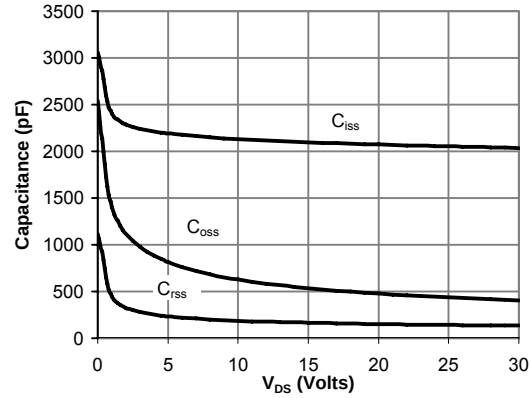
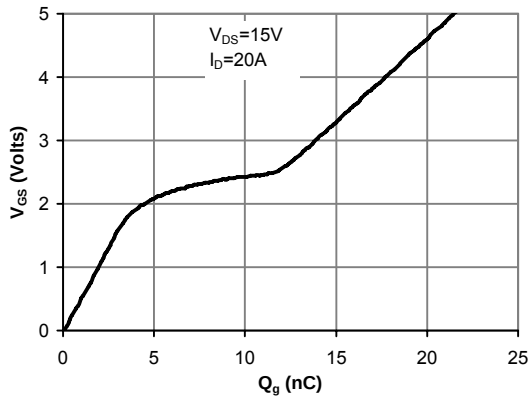


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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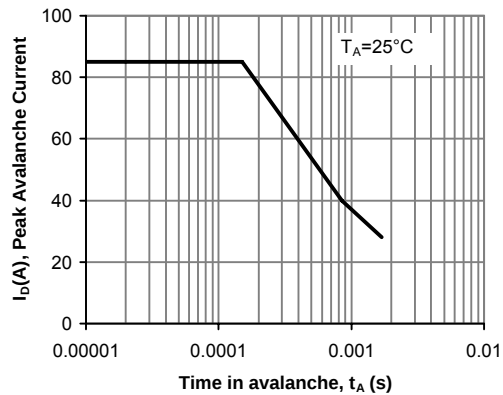


Figure 12: Single Pulse Avalanche capability

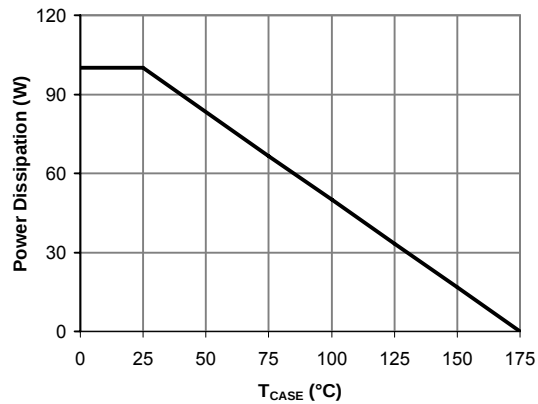


Figure 13: Power De-rating (Note B)

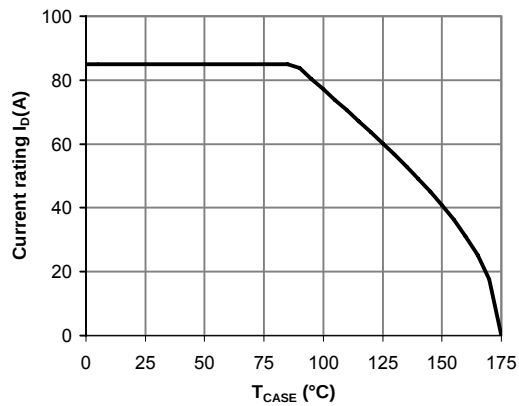


Figure 14: Current De-rating (Note B)

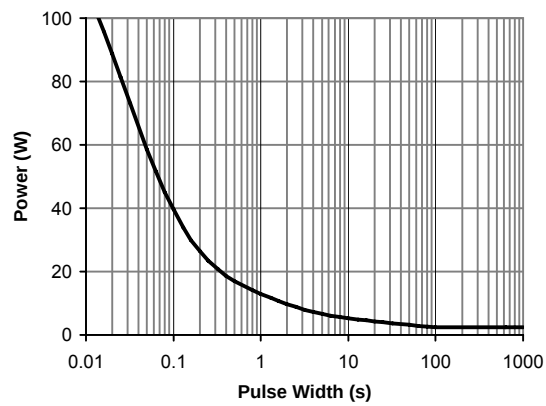


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

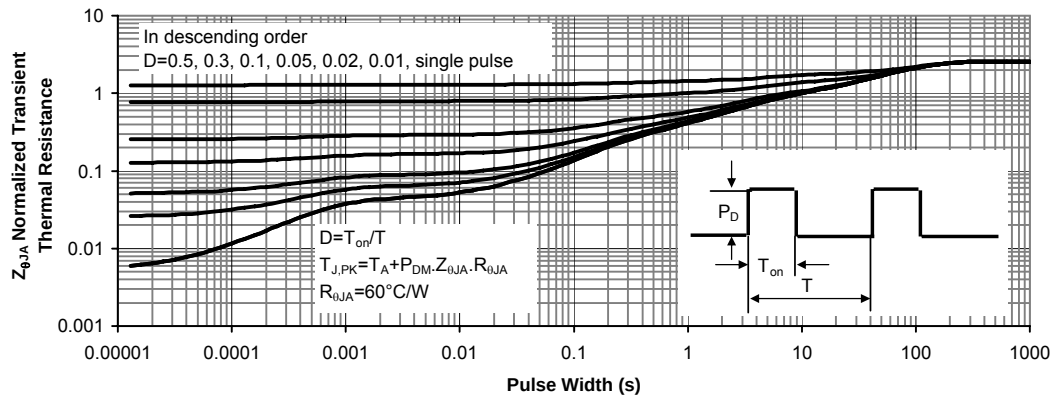


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)